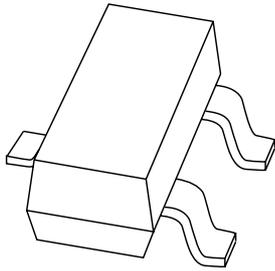


DATA SHEET



MMBT2222A NPN switching transistor

Product data sheet
Supersedes data of 2000 Apr 11

2004 Jan 16

NPN switching transistor

MMBT2222A

FEATURES

- High current (max. 600 mA)
- Low voltage (max. 40 V).

APPLICATIONS

- Switching and linear amplification.

DESCRIPTION

NPN switching transistor in a SOT23 plastic package.
PNP complement: PMBT2907A.

MARKING

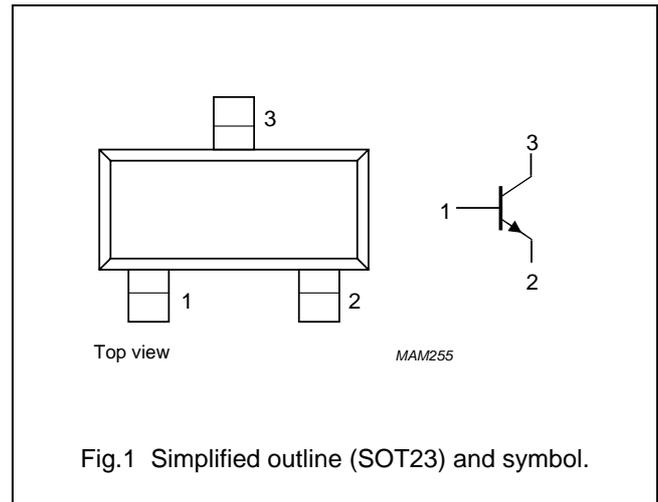
TYPE NUMBER	MARKING CODE ⁽¹⁾
MMBT2222A	7C*

Note

- * = p : Made in Hong Kong.
* = t : Made in Malaysia.
* = W : Made in China.

PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
MMBT2222A	–	plastic surface mounted package; 3 leads	SOT23

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	75	V
V_{CEO}	collector-emitter voltage	open base	–	40	V
V_{EBO}	emitter-base voltage	open collector	–	6	V
I_C	collector current (DC)		–	600	mA
I_{CM}	peak collector current		–	800	mA
I_{BM}	peak base current		–	200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$; note 1	–	250	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	150	°C
T_{amb}	operating ambient temperature		–65	+150	°C

Note

1. Transistor mounted on an FR4 printed-circuit board.

NPN switching transistor

MMBT2222A

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

CHARACTERISTICS

$T_j = 25\text{ °C}$ unless otherwise specified.

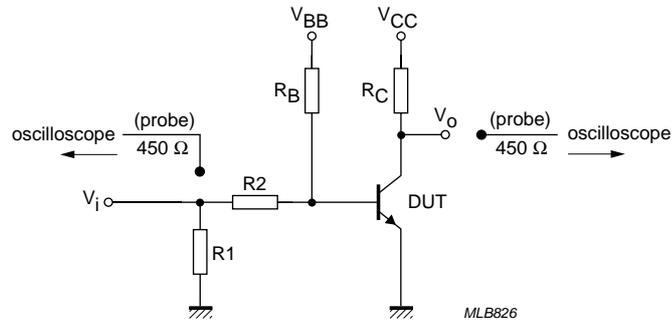
SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I_{CBO}	collector cut-off current	$I_E = 0; V_{CB} = 60\text{ V}$	–	10	nA
		$I_E = 0; V_{CB} = 60\text{ V}; T_j = 125\text{ °C}$	–	10	μA
I_{EBO}	emitter cut-off current	$I_C = 0; V_{EB} = 5\text{ V}$	–	10	nA
h_{FE}	DC current gain	$I_C = 0.1\text{ mA}; V_{CE} = 10\text{ V}$	35	–	
		$I_C = 1\text{ mA}; V_{CE} = 10\text{ V}$	50	–	
		$I_C = 10\text{ mA}; V_{CE} = 10\text{ V}$	75	–	
		$I_C = 10\text{ mA}; V_{CE} = 10\text{ V};$ $T_{amb} = -55\text{ °C}$	35	–	
		$I_C = 150\text{ mA}; V_{CE} = 10\text{ V}$	100	300	
		$I_C = 150\text{ mA}; V_{CE} = 1\text{ V}$	50	–	
		$I_C = 500\text{ mA}; V_{CE} = 10\text{ V}$	40	–	
V_{CEsat}	collector-emitter saturation voltage	$I_C = 150\text{ mA}; I_B = 15\text{ mA};$ note 1	–	300	mV
		$I_C = 500\text{ mA}; I_B = 50\text{ mA};$ note 1	–	1	V
V_{BEsat}	base-emitter saturation voltage	$I_C = 150\text{ mA}; I_B = 15\text{ mA};$ note 1	0.6	1.2	V
		$I_C = 500\text{ mA}; I_B = 50\text{ mA};$ note 1	–	2	V
C_c	collector capacitance	$I_E = i_e = 0; V_{CB} = 10\text{ V};$ $f = 1\text{ MHz}$	–	8	pF
C_e	emitter capacitance	$I_C = i_c = 0; V_{EB} = 500\text{ mV};$ $f = 1\text{ MHz}$	–	25	pF
f_T	transition frequency	$I_C = 20\text{ mA}; V_{CE} = 20\text{ V};$ $f = 100\text{ MHz}$	300	–	MHz
F	noise figure	$I_C = 100\text{ }\mu\text{A}; V_{CE} = 5\text{ V};$ $R_S = 1\text{ k}\Omega; f = 1\text{ kHz}$	–	4	dB
Switching times (between 10% and 90% levels); (see Fig.2)					
t_{on}	turn-on time	$I_{Con} = 150\text{ mA}; I_{Bon} = 15\text{ mA};$ $I_{Boff} = -15\text{ mA}$	–	35	ns
t_d	delay time		–	15	ns
t_r	rise time		–	20	ns
t_{off}	turn-off time		–	250	ns
t_s	storage time		–	200	ns
t_f	fall time		–	60	ns

Note

1. Pulse test: $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$.

NPN switching transistor

MMBT2222A



$V_i = 9.5 \text{ V}$; $T = 500 \text{ } \mu\text{s}$; $t_p = 10 \text{ } \mu\text{s}$; $t_r = t_f \leq 3 \text{ ns}$.
 $R_1 = 68 \text{ } \Omega$; $R_2 = 325 \text{ } \Omega$; $R_B = 325 \text{ } \Omega$; $R_C = 160 \text{ } \Omega$.
 $V_{BB} = -3.5 \text{ V}$; $V_{CC} = 29.5 \text{ V}$.
Oscilloscope: input impedance $Z_i = 50 \text{ } \Omega$.

Fig.2 Test circuit for switching times.

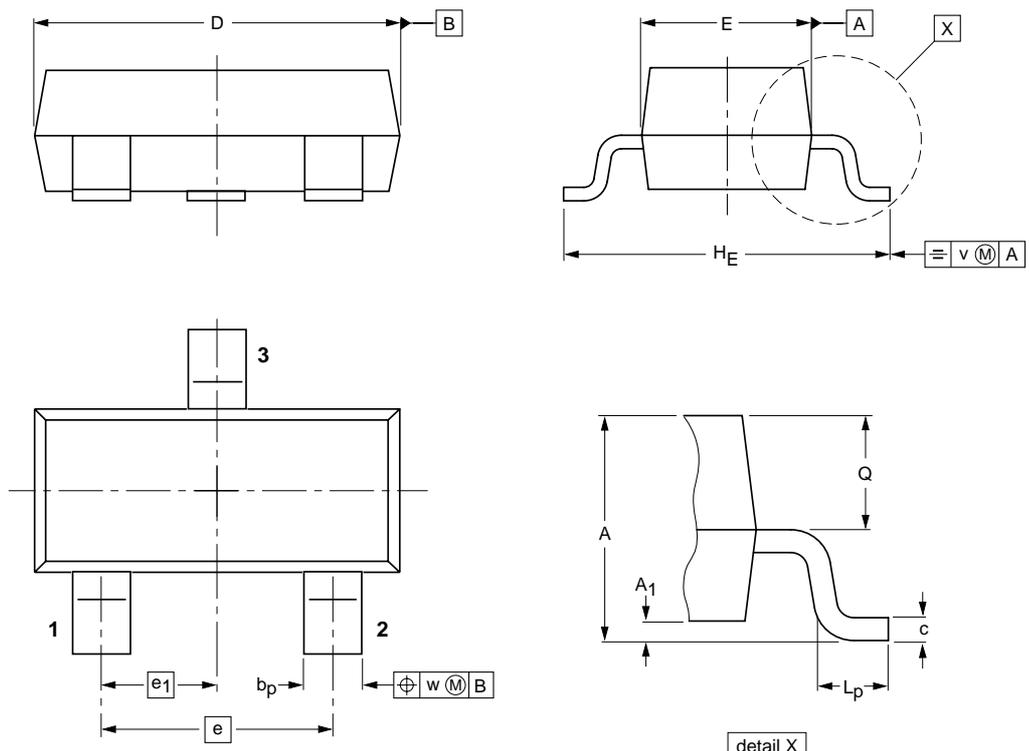
NPN switching transistor

MMBT2222A

PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads

SOT23



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max.	b _p	c	D	E	e	e ₁	H _E	L _p	Q	v	w
mm	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT23		TO-236AB				04-11-04 06-03-16

MMBT2222L, MMBT2222AL, SMMBT2222AL

General Purpose Transistors

NPN Silicon

Features

- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage MMBT2222L MMBT2222AL, SMMBT2222AL	V_{CEO}	30 40	Vdc
Collector-Base Voltage MMBT2222L MMBT2222AL, SMMBT2222AL	V_{CBO}	60 75	Vdc
Emitter-Base Voltage MMBT2222L MMBT2222AL, SMMBT2222AL	V_{EBO}	5.0 6.0	Vdc
Collector Current - Continuous	I_C	600	mAdc
Collector Current - Peak (Note 3)	I_{CM}	1100	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	225 1.8	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	$^\circ\text{C}/\text{W}$
Total Device Dissipation Alumina Substrate (Note 2) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	300 2.4	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

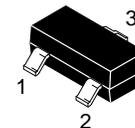
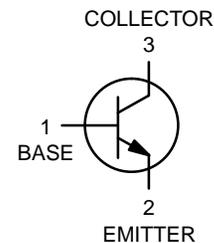
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.
2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.
3. Reference SOA curve.



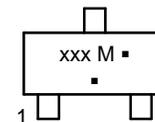
ON Semiconductor®

www.onsemi.com



SOT-23
CASE 318
STYLE 6

MARKING DIAGRAM



xxx = 1P or M1B
M = Date Code*
▪ = Pb-Free Package

(Note: Microdot may be in either location)
*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

MMBT2222L, MMBT2222AL, SMMBT2222AL

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS					
Collector–Emitter Breakdown Voltage (I _C = 10 mA _{dc} , I _B = 0)	MMBT2222 MMBT2222A	V _{(BR)CEO}	30 40	– –	V _{dc}
Collector–Base Breakdown Voltage (I _C = 10 μA _{dc} , I _E = 0)	MMBT2222 MMBT2222A	V _{(BR)CBO}	60 75	– –	V _{dc}
Emitter–Base Breakdown Voltage (I _E = 10 μA _{dc} , I _C = 0)	MMBT2222 MMBT2222A	V _{(BR)EBO}	5.0 6.0	– –	V _{dc}
Collector Cutoff Current (V _{CE} = 60 V _{dc} , V _{EB(off)} = 3.0 V _{dc})	MMBT2222A, SMMBT2222A	I _{CEX}	–	10	nA _{dc}
Collector Cutoff Current (V _{CB} = 50 V _{dc} , I _E = 0)	MMBT2222 MMBT2222A, SMMBT2222A	I _{CBO}	–	0.01	μA _{dc}
(V _{CB} = 60 V _{dc} , I _E = 0)	MMBT2222A, SMMBT2222A		–	0.01	
(V _{CB} = 50 V _{dc} , I _E = 0, T _A = 125°C)	MMBT2222		–	10	
(V _{CB} = 60 V _{dc} , I _E = 0, T _A = 125°C)	MMBT2222A, SMMBT2222A		–	10	
Emitter Cutoff Current (V _{EB} = 3.0 V _{dc} , I _C = 0)	MMBT2222A, SMMBT2222A	I _{EBO}	–	100	nA _{dc}
Base Cutoff Current (V _{CE} = 60 V _{dc} , V _{EB(off)} = 3.0 V _{dc})	MMBT2222A, SMMBT2222A	I _{BL}	–	20	nA _{dc}
ON CHARACTERISTICS					
DC Current Gain (I _C = 0.1 mA _{dc} , V _{CE} = 10 V _{dc}) (I _C = 1.0 mA _{dc} , V _{CE} = 10 V _{dc}) (I _C = 10 mA _{dc} , V _{CE} = 10 V _{dc}) (I _C = 10 mA _{dc} , V _{CE} = 10 V _{dc} , T _A = –55°C) (I _C = 150 mA _{dc} , V _{CE} = 10 V _{dc}) (Note 4) (I _C = 150 mA _{dc} , V _{CE} = 1.0 V _{dc}) (Note 4) (I _C = 500 mA _{dc} , V _{CE} = 10 V _{dc}) (Note 4)	MMBT2222A only MMBT2222 MMBT2222A, SMMBT2222A	h _{FE}	35 50 75 35 100 50 30 40	– – – – 300 – – –	–
Collector–Emitter Saturation Voltage (Note 4) (I _C = 150 mA _{dc} , I _B = 15 mA _{dc}) (I _C = 500 mA _{dc} , I _B = 50 mA _{dc})	MMBT2222 MMBT2222A, SMMBT2222A MMBT2222 MMBT2222A, SMMBT2222A	V _{CE(sat)}	– – – –	0.4 0.3 1.6 1.0	V _{dc}
Base–Emitter Saturation Voltage (Note 4) (I _C = 150 mA _{dc} , I _B = 15 mA _{dc}) (I _C = 500 mA _{dc} , I _B = 50 mA _{dc})	MMBT2222 MMBT2222A, SMMBT2222A MMBT2222 MMBT2222A, SMMBT2222A	V _{BE(sat)}	– 0.6 – –	1.3 1.2 2.6 2.0	V _{dc}
SMALL–SIGNAL CHARACTERISTICS					
Current–Gain – Bandwidth Product (Note 5) (I _C = 20 mA _{dc} , V _{CE} = 20 V _{dc} , f = 100 MHz)	MMBT2222 MMBT2222A, SMMBT2222A	f _T	250 300	– –	MHz
Output Capacitance (V _{CB} = 10 V _{dc} , I _E = 0, f = 1.0 MHz)		C _{obo}	–	8.0	pF
Input Capacitance (V _{EB} = 0.5 V _{dc} , I _C = 0, f = 1.0 MHz)	MMBT2222 MMBT2222A, SMMBT2222A	C _{ibo}	– –	30 25	pF
Input Impedance (I _C = 1.0 mA _{dc} , V _{CE} = 10 V _{dc} , f = 1.0 kHz) (I _C = 10 mA _{dc} , V _{CE} = 10 V _{dc} , f = 1.0 kHz)	MMBT2222A, SMMBT2222A MMBT2222A, SMMBT2222A	h _{ie}	2.0 0.25	8.0 1.25	kΩ
Voltage Feedback Ratio (I _C = 1.0 mA _{dc} , V _{CE} = 10 V _{dc} , f = 1.0 kHz) (I _C = 10 mA _{dc} , V _{CE} = 10 V _{dc} , f = 1.0 kHz)	MMBT2222A, SMMBT2222A MMBT2222A, SMMBT2222A	h _{re}	– –	8.0 4.0	X 10 ^{–4}
Small–Signal Current Gain (I _C = 1.0 mA _{dc} , V _{CE} = 10 V _{dc} , f = 1.0 kHz) (I _C = 10 mA _{dc} , V _{CE} = 10 V _{dc} , f = 1.0 kHz)	MMBT2222A, SMMBT2222A MMBT2222A, SMMBT2222A	h _{fe}	50 75	300 375	–

MMBT2222L, MMBT2222AL, SMMBT2222AL

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
SMALL-SIGNAL CHARACTERISTICS				
Output Admittance ($I_C = 1.0\text{ mA dc}$, $V_{CE} = 10\text{ V dc}$, $f = 1.0\text{ kHz}$) ($I_C = 10\text{ mA dc}$, $V_{CE} = 10\text{ V dc}$, $f = 1.0\text{ kHz}$)	h_{oe}	5.0 25	35 200	μmhos
Collector Base Time Constant ($I_E = 20\text{ mA dc}$, $V_{CB} = 20\text{ V dc}$, $f = 31.8\text{ MHz}$)	r_b, C_c	-	150	ps
Noise Figure ($I_C = 100\text{ }\mu\text{A dc}$, $V_{CE} = 10\text{ V dc}$, $R_S = 1.0\text{ k}\Omega$, $f = 1.0\text{ kHz}$)	NF	-	4.0	dB

SWITCHING CHARACTERISTICS (MMBT2222A only)

Delay Time	$(V_{CC} = 30\text{ V dc}$, $V_{BE(\text{off})} = -0.5\text{ V dc}$, $I_C = 150\text{ mA dc}$, $I_{B1} = 15\text{ mA dc}$)	t_d	-	10	ns
Rise Time		t_r	-	25	
Storage Time	$(V_{CC} = 30\text{ V dc}$, $I_C = 150\text{ mA dc}$, $I_{B1} = I_{B2} = 15\text{ mA dc}$)	t_s	-	225	ns
Fall Time		t_f	-	60	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- Pulse Test: Pulse Width $\leq 300\text{ }\mu\text{s}$, Duty Cycle $\leq 2.0\%$.
- f_T is defined as the frequency at which $|h_{fe}|$ extrapolates to unity.

SWITCHING TIME EQUIVALENT TEST CIRCUITS

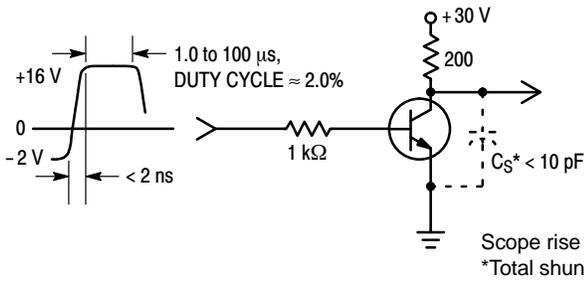


Figure 1. Turn-On Time

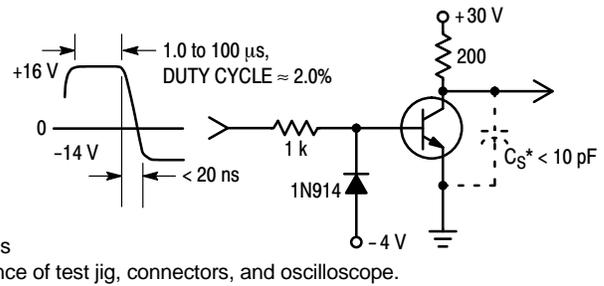


Figure 2. Turn-Off Time

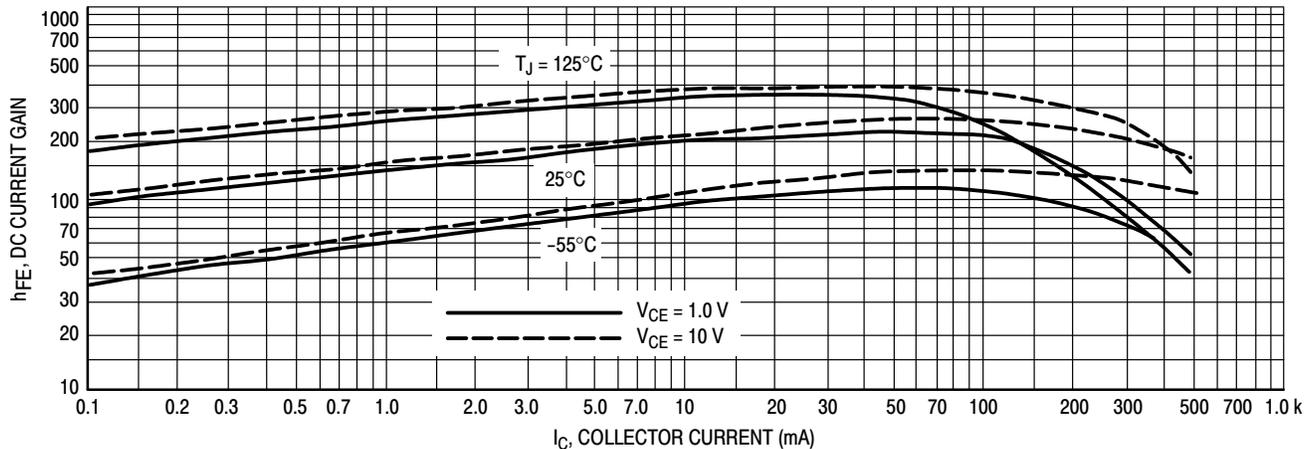


Figure 3. DC Current Gain

MMBT2222L, MMBT2222AL, SMMBT2222AL

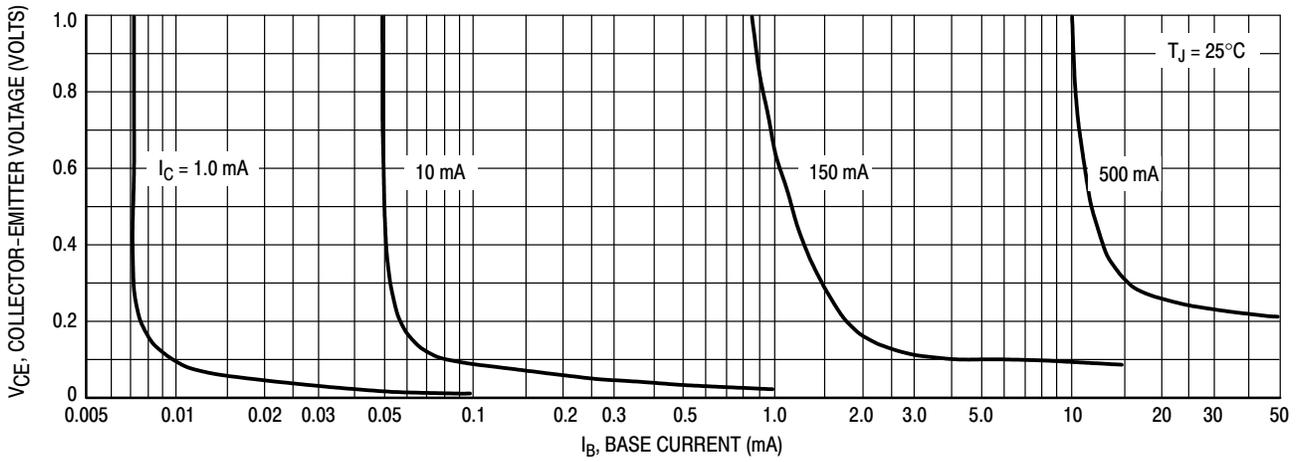


Figure 4. Collector Saturation Region

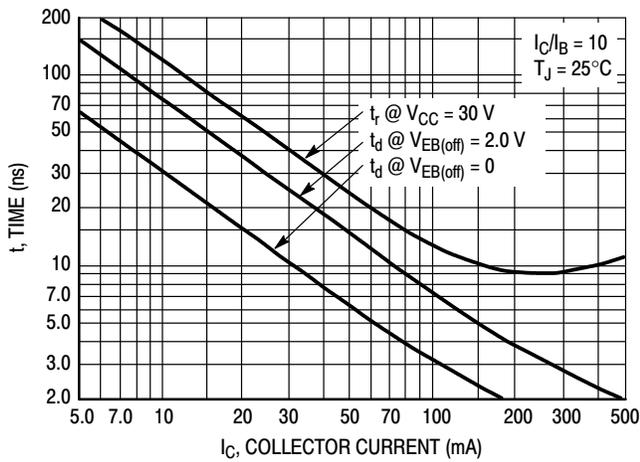


Figure 5. Turn-On Time

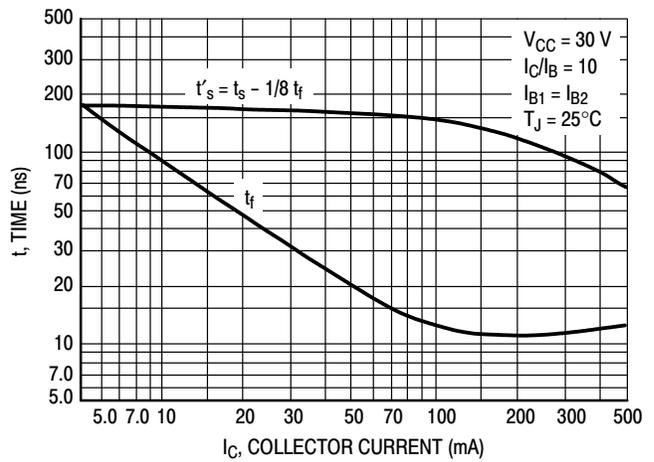


Figure 6. Turn-Off Time

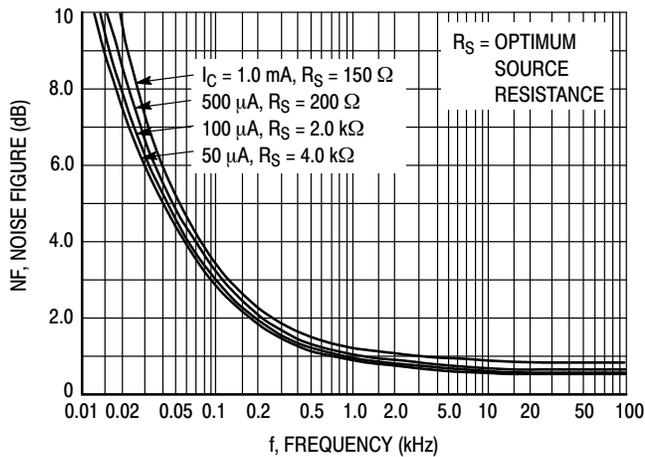


Figure 7. Frequency Effects

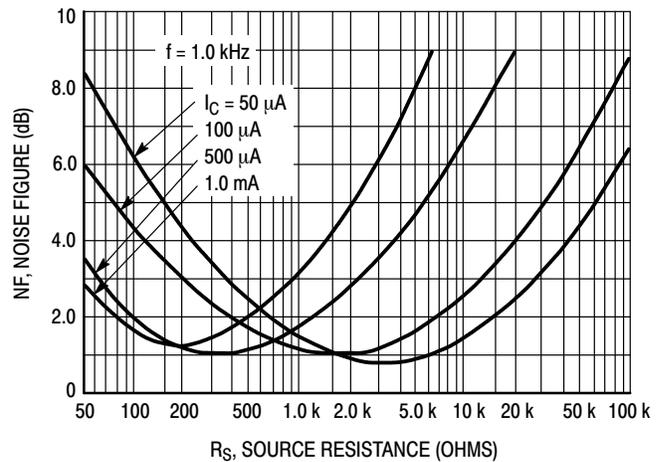


Figure 8. Source Resistance Effects

MMBT2222L, MMBT2222AL, SMMBT2222AL

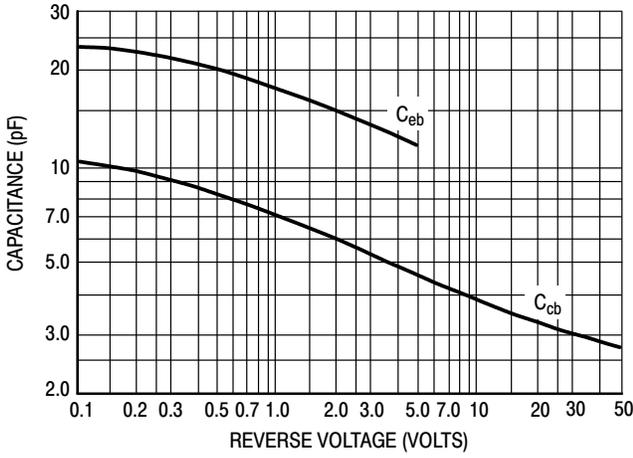


Figure 9. Capacitances

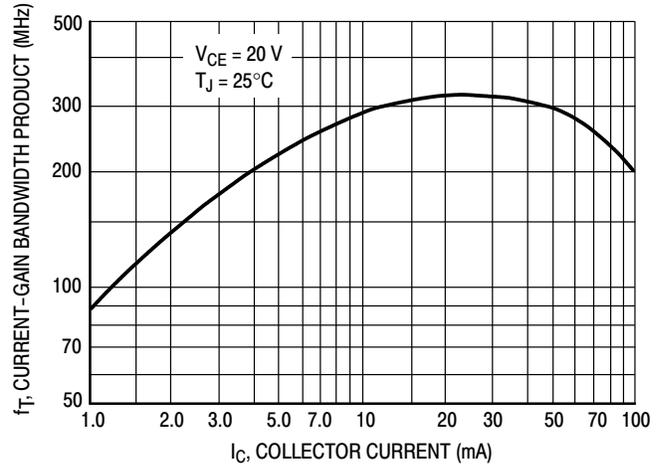


Figure 10. Current-Gain Bandwidth Product

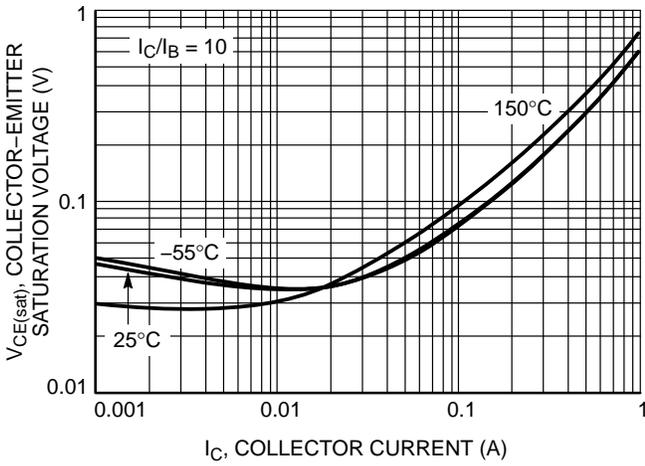


Figure 11. Collector-Emitter Saturation Voltage vs. Collector Current

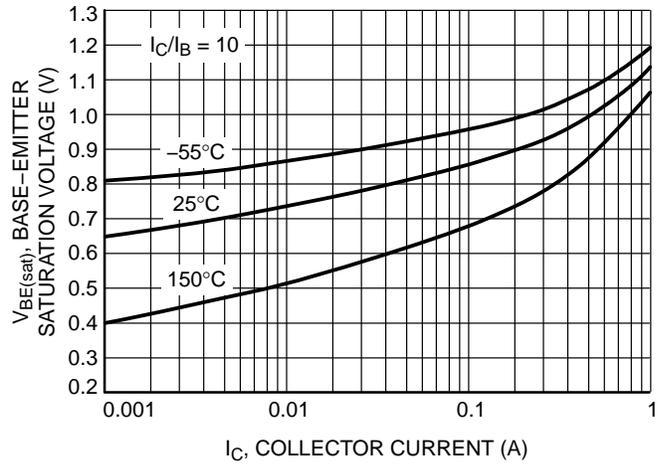


Figure 12. Base-Emitter Saturation Voltage vs. Collector Current

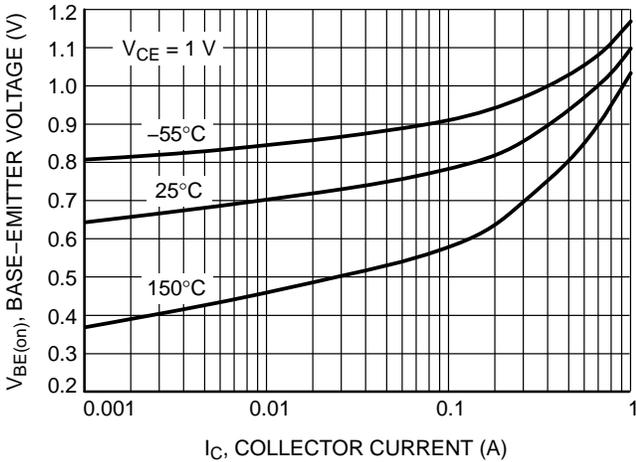


Figure 13. Base-Emitter Voltage vs. Collector Current

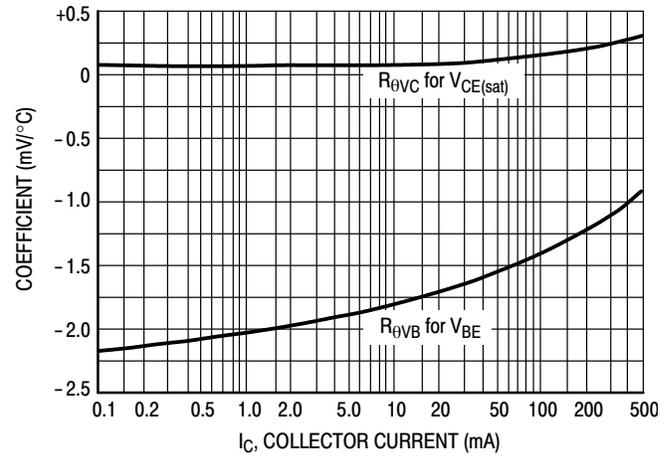


Figure 14. Temperature Coefficients

MMBT2222L, MMBT2222AL, SMMBT2222AL

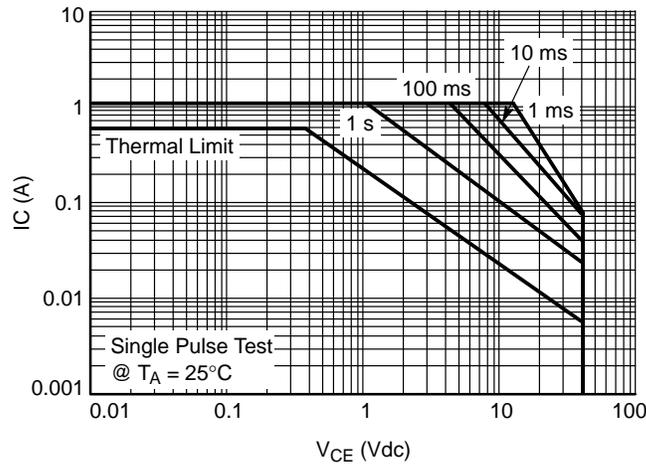


Figure 15. Safe Operating Area

ORDERING INFORMATION

Device	Specific Marking Code	Package	Shipping†
MMBT2222LT1G	M1B	SOT-23 (Pb-Free)	3000 / Tape & Reel
MMBT2222ALT1G, SMMBT2222ALT1G	1P	SOT-23 (Pb-Free)	3000 / Tape & Reel
MMBT2222LT3G	M1B	SOT-23 (Pb-Free)	10,000 / Tape & Reel
MMBT2222ALT3G, SMMBT2222ALT3G	1P	SOT-23 (Pb-Free)	10,000 / Tape & Reel

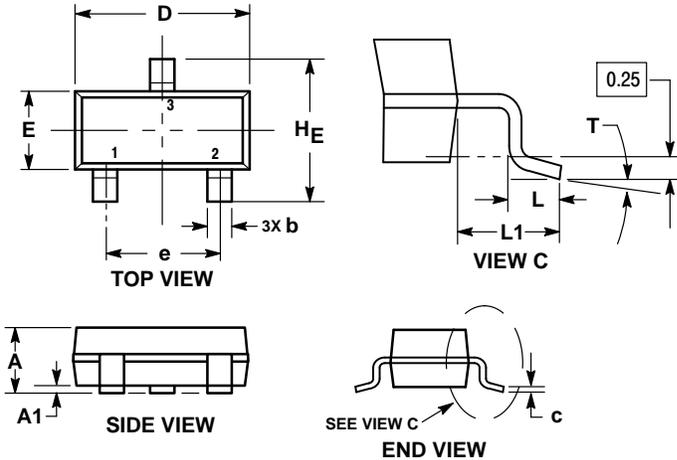
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

MMBT2222L, MMBT2222AL, SMMBT2222AL

PACKAGE DIMENSIONS

SOT-23 (TO-236)
CASE 318-08
ISSUE AR



NOTES:

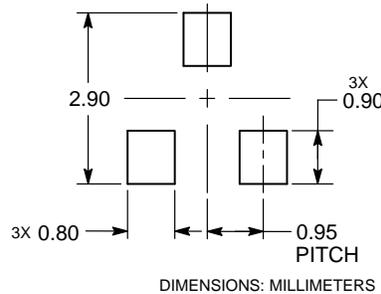
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
c	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
T	0°	---	10°	0°	---	10°

STYLE 6:

1. BASE
2. EMITTER
3. COLLECTOR

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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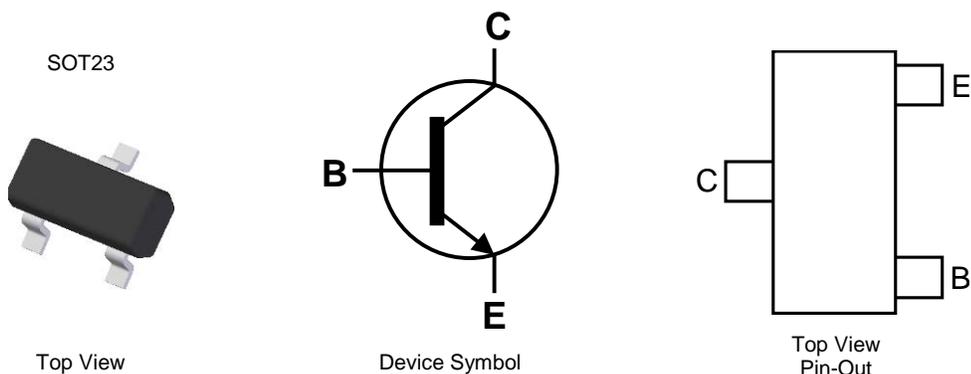
For additional information, please contact your local Sales Representative

Features

- Epitaxial Planar Die Construction
- Complementary PNP Type: MMBT2907A
- Ideal for Low Power Amplification and Switching
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish; Solderable per MIL-STD-202, Method 208
- Weight: 0.008 grams (Approximate)

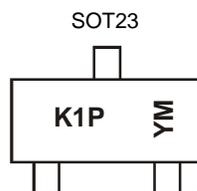


Ordering Information (Notes 4 & 5)

Product	Status	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
MMBT2222A-7-F	Active	AEC-Q101	K1P	7	8	3,000
MMBT2222A-13-F	Active	AEC-Q101	K1P	13	8	10,000
MMBT2222AQ-7-F	Active	Automotive	K1P	7	8	3,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/product_compliance_definitions.html.
 5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



K1P = Product Type Marking Code
 YM = Date Code Marking
 Y or \bar{Y} = Year (ex: D = 2016)
 M or \bar{M} = Month (ex: 9 = September)

Date Code Key

Year	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024
Code	C	D	E	F	G	H	I	J	K	L

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	75	V
Collector-Emitter Voltage	V _{CEO}	40	V
Emitter-Base Voltage	V _{EBO}	6.0	V
Collector Current	I _C	600	mA
Peak Collector Current	I _{CM}	800	mA
Peak Base Current	I _{BM}	200	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

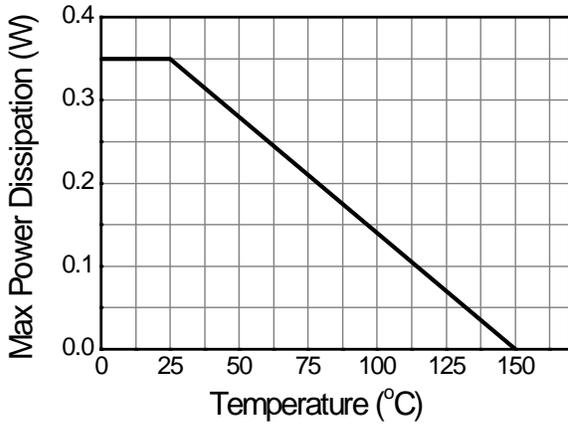
Characteristic	Symbol	Value	Unit
Collector Power Dissipation	P _D	(Note 6) 310	mW
		(Note 7) 350	
Thermal Resistance, Junction to Ambient	R _{θJA}	(Note 6) 403	°C/W
		(Note 7) 357	
Thermal Resistance, Junction to Leads	R _{θJL}	350	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

ESD Ratings (Note 9)

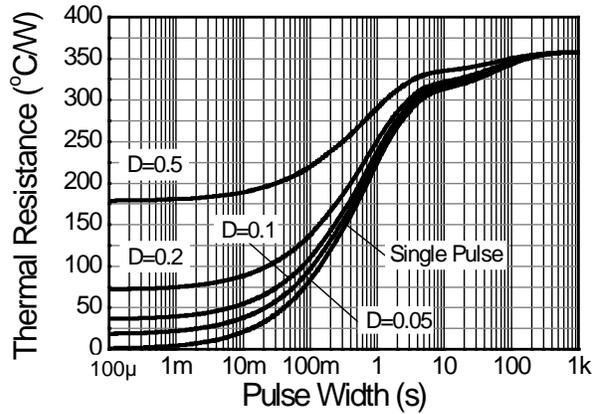
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
6. For a device mounted on minimum recommended pad layout 1oz copper that is on a single-sided FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.
 7. Same as Note 6, except the device is mounted on 15 mm x 15mm 1oz copper.
 8. Thermal resistance from junction to solder-point (at the end of the leads).
 9. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

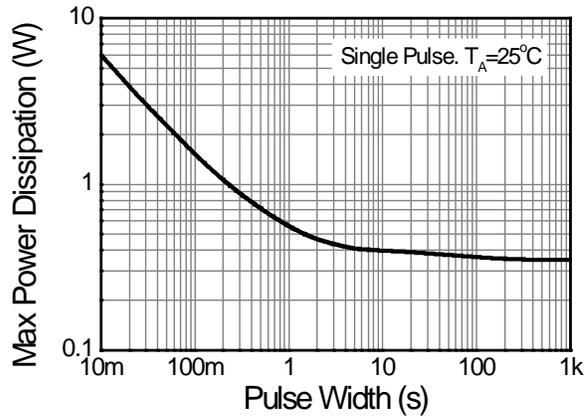
Thermal Characteristics and Derating Information



Derating Curve



Transient Thermal Impedance



Pulse Power Dissipation

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS					
Collector-Base Breakdown Voltage	BV_{CBO}	75	—	V	$I_C = 100\mu\text{A}$, $I_E = 0$
Collector-Emitter Breakdown Voltage (Note 10)	BV_{CEO}	40	—	V	$I_C = 10\text{mA}$, $I_B = 0$
Emitter-Base Breakdown Voltage	BV_{EBO}	6.0	—	V	$I_E = 100\mu\text{A}$, $I_C = 0$
Collector Cut-Off Current	I_{CBO}	—	10	nA μA	$V_{CB} = 60\text{V}$, $I_E = 0$ $V_{CB} = 60\text{V}$, $I_E = 0$, $T_A = +150^\circ\text{C}$
Collector Cut-Off Current	I_{CEX}	—	10	nA	$V_{CE} = 60\text{V}$, $V_{EB(OFF)} = 3.0\text{V}$
Collector Cut-Off Current	I_{CEV}	—	10	nA	$V_{CE} = 60\text{V}$, $V_{BE} = \pm 0.25\text{V}$
Emitter Cut-Off Current	I_{EBO}	—	10	nA	$V_{EB} = 5.0\text{V}$, $I_C = 0$
Base Cut-Off Current	I_{BL}	—	20	nA	$V_{CE} = 60\text{V}$, $V_{EB(OFF)} = 3.0\text{V}$
ON CHARACTERISTICS (Note 10)					
DC Current Gain	h_{FE}	35 50 75 100 40 50 35	— — — 300 — — —	—	$I_C = 100\mu\text{A}$, $V_{CE} = 10\text{V}$ $I_C = 1.0\text{mA}$, $V_{CE} = 10\text{V}$ $I_C = 10\text{mA}$, $V_{CE} = 10\text{V}$ $I_C = 150\text{mA}$, $V_{CE} = 10\text{V}$ $I_C = 500\text{mA}$, $V_{CE} = 10\text{V}$ $I_C = 10\text{mA}$, $V_{CE} = 10\text{V}$, $T_A = -55^\circ\text{C}$ $I_C = 150\text{mA}$, $V_{CE} = 1.0\text{V}$
Collector-Emitter Saturation Voltage	$V_{CE(SAT)}$	—	0.3 1.0	V	$I_C = 150\text{mA}$, $I_B = 15\text{mA}$ $I_C = 500\text{mA}$, $I_B = 50\text{mA}$
Base-Emitter Saturation Voltage	$V_{BE(SAT)}$	0.6 —	1.2 2.0	V	$I_C = 150\text{mA}$, $I_B = 15\text{mA}$ $I_C = 500\text{mA}$, $I_B = 50\text{mA}$
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance	C_{obo}	—	8	pF	$V_{CB} = 10\text{V}$, $f = 1.0\text{MHz}$, $I_E = 0$
Input Capacitance	C_{ibo}	—	25	pF	$V_{EB} = 0.5\text{V}$, $f = 1.0\text{MHz}$, $I_C = 0$
Current Gain-Bandwidth Product	f_T	300	—	MHz	$V_{CE} = 20\text{V}$, $I_C = 20\text{mA}$, $f = 100\text{MHz}$
Noise Figure	N_F	—	4.0	dB	$V_{CE} = 10\text{V}$, $I_C = 100\mu\text{A}$, $R_S = 1.0\text{k}\Omega$, $f = 1.0\text{kHz}$
SWITCHING CHARACTERISTICS					
Delay Time	t_D	—	10	ns	$V_{CC} = 30\text{V}$, $I_C = 150\text{mA}$, $V_{BE(OFF)} = -0.5\text{V}$, $I_{B1} = 15\text{mA}$
Rise Time	t_R	—	25	ns	$V_{CC} = 3.0\text{V}$, $I_C = 150\text{mA}$, $I_{B1} = 15\text{mA}$, $V_{BE(OFF)} = 0.5\text{V}$
Storage Time	t_S	—	225	ns	$V_{CC} = 30\text{V}$, $I_C = 150\text{mA}$, $I_{B1} = I_{B2} = 15\text{mA}$
Fall Time	t_F	—	60	ns	$V_{CC} = 30\text{V}$, $I_C = 150\text{mA}$, $I_{B1} = I_{B2} = 15\text{mA}$

 Note: 10. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.

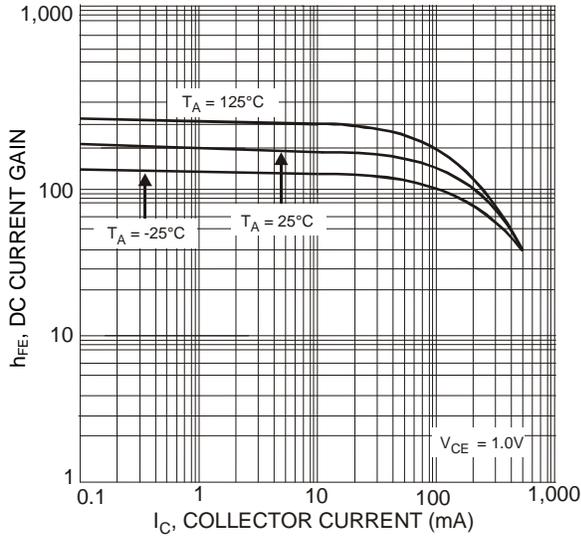


Figure 1 Typical DC Current Gain vs. Collector Current

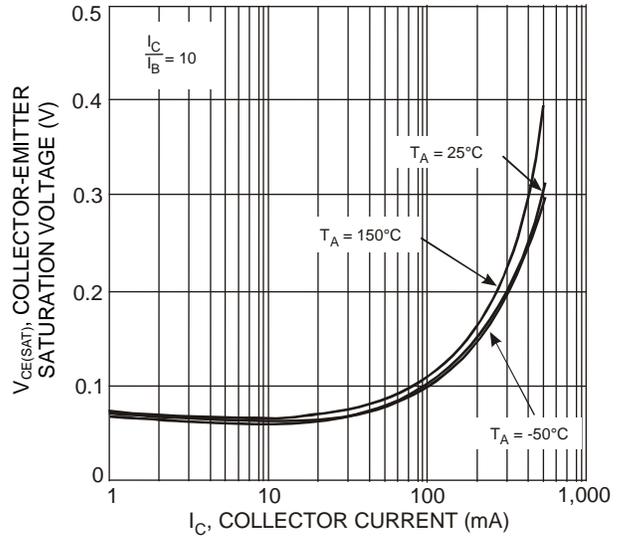


Figure 2 Typical Collector-Emitter Saturation Voltage vs. Collector Current

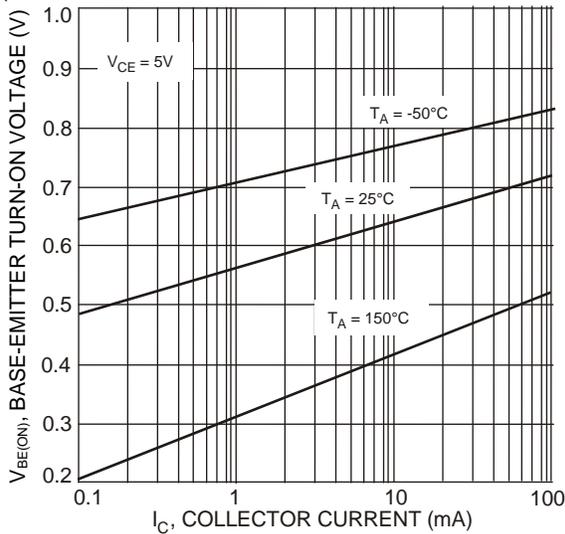


Figure 3 Base-Emitter Turn-On Voltage vs. Collector Current

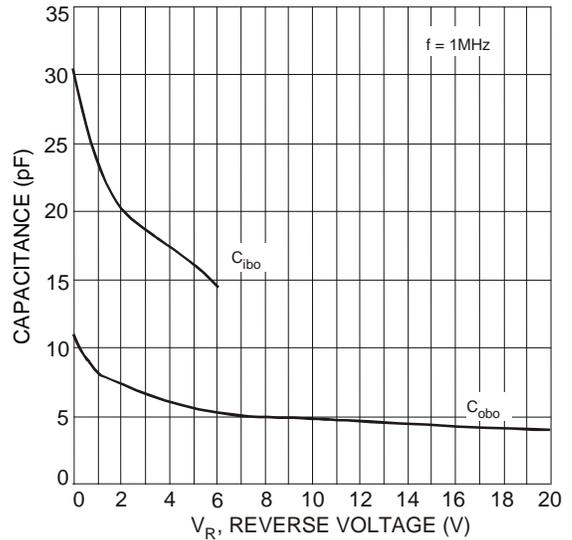


Figure 4 Typical Capacitance Characteristics

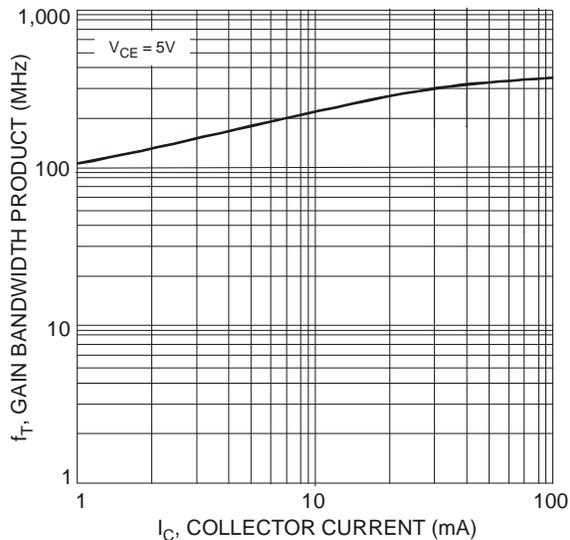


Figure 5 Typical Gain Bandwidth Product vs. Collector Current

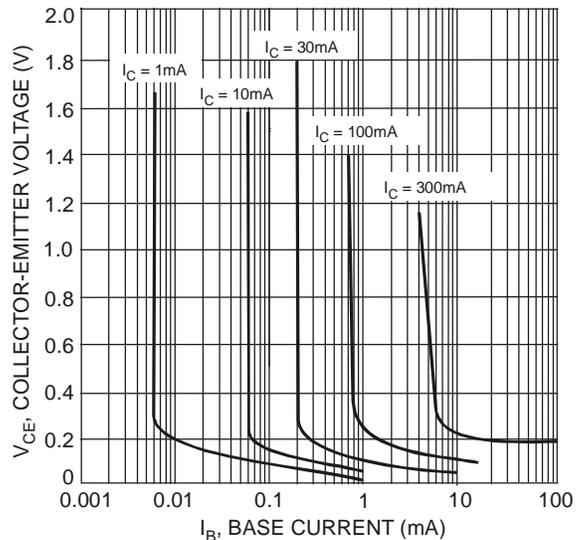
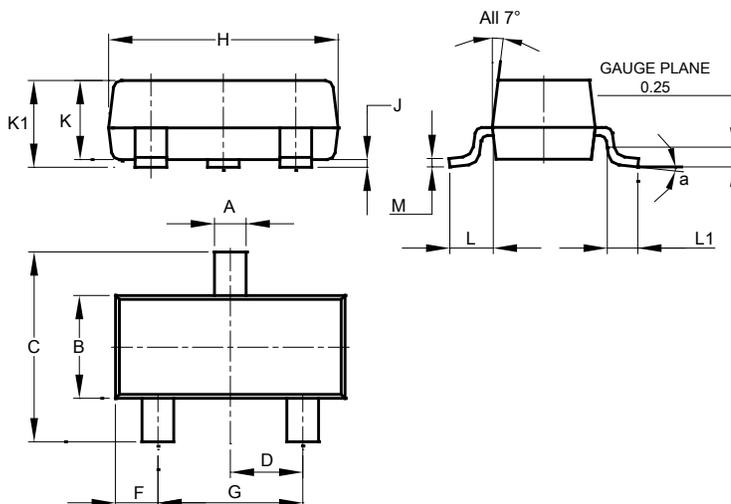


Figure 6 Typical Collector Saturation Region

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT23

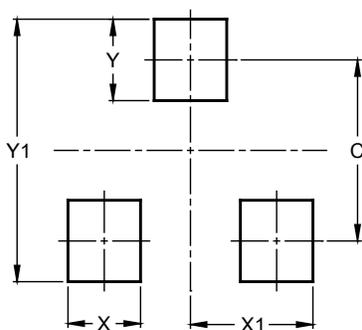


SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
a	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT23



Dimensions	Value (in mm)
C	2.0
X	0.8
X1	1.35
Y	0.9
Y1	2.9

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